

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

Taiwan Semiconductor Manufacturing Company Ltd.,

Petitioner,

v.

Advanced Integrated Circuit Process LLC,

Patent Owner.

IPR2025-01211

U.S. Patent No. 7,439,623

**PETITIONER'S UPDATED EXHIBIT
LIST**

UPDATED EXHIBIT LIST

Exhibit No.	Description	Filed	Served
1001	U.S. Patent No. 7,439,623	X	X
1002	File History of U.S. Patent No. 7,439,623 (“623 File History”)	X	X
1003	Declaration of Dr. Reinhold Dauskardt	X	X
1004	U.S. Patent Publication No. 2003/0116852 to Watanabe et al. (“Watanabe”)	X	X
1005	U.S. Patent Publication No. 2004/0113238 to Hasunuma et al. (“Hasunuma”)	X	X
1006	Reserved		
1007	U.S. Patent No. 6,717,267 to Kunikiyo (“Kunikiyo”)	X	X
1008	U.S. Patent No. 5,250,465 to Iizuka et al. (“Iizuka”)	X	X
1009	U.S. Patent Publication No. 2004/0173905 to Kamoshima et al. (“Kamoshima”)	X	X
1010	JP2002299437 (“Fukazawa”) and Certified Translation of Fukazawa with Certification of Translation	X	X
1011	U.S. Patent No. 7,042,099 to Kurashima (“Kurashima”)	X	X
1012	P. Andricacos, “Copper On-Chip Interconnections,” <i>Interface, The Electrochemical Society</i> , pp. 32-37, 1999	X	X
1013	U.S. Patent No. 5,885,857 to Yamaha et al. (“Yamaha”)	X	X

Exhibit No.	Description	Filed	Served
1014	U.S. Patent Publication No. 2003/0005399 to Igarashi ("Igarashi")	X	X
1015	U.S. Patent No. 6,717,268 to Hau-Riege ("Hau-Riege")	X	X
1016	U.S. Patent No. 6,468,894 to Yang ("Yang")	X	X
1017	U.S. Patent No. 6,022,808 to Nogami ("Nogami")	X	X
1018	AICP'S P.R. 3-1 Disclosure of Asserted Claims and Infringement Contentions and P.R. 3-2 Document Production Against TSMC (cover document only)	X	X
1019	Kaanta et al., "Dual Damascene: A ULSI Wiring Technology," <i>VMIC Conference</i> , IEEE, Jun. 11-12, 1991, pp. 144-152	X	X
1020	U.S. Patent No. 5,032,890 to Ushiku ("Ushiku")	X	X
1021	Reserved		
1022	Reserved		
1023	Reserved		
1024	U.S. Patent No. 6,156,660 to Liu et al. ("Liu")	X	X
1025	U.S. Patent No. 5,798,298 to Yang ("Yang 2")	X	X
1026	T. I. Bao et al., "90 nm Generation Cu/CVD Low-k ($k < 2.5$) Interconnect Technology," <i>Digest. International Electron Devices Meeting</i> , San Francisco, CA, USA,	X	X

Exhibit No.	Description	Filed	Served
	2002, pp. 583-586		
1027	A. Loke, "Process Integration Issues of Low-Permittivity Dielectrics With Copper for High-Performance Interconnects, Dissertation," Stanford University (1999)	X	X
1028	K.N. Tu, "Recent advances on electromigration in very-large- scale-integration of interconnects," <i>Applied Physics Review – Focused Review, Journal of Applied Physics</i> , Vol. 94, No. 9, pp. 5451-5473 (November 1, 2003)	X	X
1029	T. C. Huang, et al., "Numerical Modeling and Characterization of the Stress Migration Behaviour Upon Various 90 nanometer Cu/Low k Interconnects," <i>Proceedings of the IEEE 2003 International Interconnect Technology Conference (Cat. No.03TH8695)</i> , Burlingame, CA, USA, 2003 (added to IEEE Xplore 8-11-2003), pp. 207-209	X	X
1030	JPH10214893 to Fujii ("Fujii") and Certified Translation of Fujii with Certification of Translation	X	X
1031	Reserved		
1032	JP2000012688 to Nasu ("Nasu") and Certified Translation of Nasu with Certification of Translation	X	X
1033	U.S. Patent Publication No. 2001/0030365 to Otsuka et al. ("Otsuka")	X	X
1034	Wolf, Stanley, <i>Silicon Processing for the VLSI Era: Deep- Submicron Process Technology</i> , Lattice Press,	X	X

Exhibit No.	Description	Filed	Served
	2002 (excerpted) (“Wolf”)		
1035	Reserved		
1036	Ogawa, E.T., et al., “Stress-Induced Voiding Under Vias Connected To Wide Cu Metal Leads,” IEEE 02CH37320, 40 th Annual International Reliability Physics Symposium, Dallas, Texas, 2002, pp. 312-21	X	X
1037	A. von Glasow et al., “Geometrical Aspects of Stress-Induced Voiding in Copper Interconnects,” Proceedings of the Advanced Metallization Conference 2002 (AMC 2002), San Diego, CA, October 1-3, 2002, Tokyo, Japan, October 29-30, 2002, Materials Research Society, pp. 161-67	X	X
1038	U.S. Patent No. 6,215,189 to Toyoda et al. (“Toyoda”)	X	X
1039	U.S. Patent No. 6,238,850 to Bula et al. (“Bula”)	X	X
1040	STIPULATION: 7-31-2025 Letter from K. Wheatley (counsel for TSMC) to J. Nelson et al. (counsel for AICP)	X	X
1041	Patent Assignment Record from Nuvoton Technology Corp. Japan to Advanced Integrated Circuit Process LLC, Reel: 068118 Frame: 0314-0317, United States Patent and Trademark Office (July 30, 2024)	X	X
1042	United States District Courts – National Judicial Caseload Profile, 12-Month Period Ending Mar. 31, 2025, U.S. Courts (2025), available at https://www.uscourts.gov/sites/default/files/document/fcms_na_distprofile0331.2025.pdf	X	X

Exhibit No.	Description	Filed	Served
1043	Summary of Judge Gilstrap Patent Trials Between October 22, 2024 and October 22, 2025	X	X
1044	Docket for 2:23-cv-00274 (E.D. Tex.)	X	X
1045	Docket for 2:23-cv-0379 (E.D. Tex.)	X	X
1046	Docket for 2:24-cv-00034 (E.D. Tex.)	X	X
1047	Docket for 2:24-cv-00047 (E.D. Tex.)	X	X
1048	Docket for 2:24-cv-00049 (E.D. Tex.)	X	X
1049	Jeremy Bowman, Nasdaq, This 1 Number May Ensure TSMC's Market Dominance, The Motley Fool (Aug. 17, 2024) (last visited October 22, 2025), available at https://www.nasdaq.com/articles/1-number-may-ensure-tsmcs-market-dominance	X	X
1050	CNBC Transcript: United States Commerce Secretary Howard Lutnick Speaks with CNBC's Brian Sullivan on "The Exchange" Today, CNBC (Apr. 29, 2025) (last visited October 22, 2025), available at https://www.cnbc.com/2025/04/29/cnbc-transcript-united-states-commerce-secretary-howard-lutnick-speaks-with-cnbc-brian-sullivan-on-the-exchange-today.html	X	X
1051	Trump on China Putting - America First (Robert C. O'Brien editor)	X	X
1052	Remarks: Donald Trump Announces an Economic Investment in the United States - March 3, 2025, available at https://rollcall.com/factbase/trump/transcript/donald-trump-remarks-economic-investment-united-states-	X	X

Exhibit No.	Description	Filed	Served
	march-3-2025/#2		
1053	Speech: Donald Trump Addresses an Republican Dinner in Washington - April 8, 2025, available at https://rollcall.com/factbase/trump/transcript/donald-trump-speech-nrcc-republican-dinner-april-8-2025/#161	X	X
1054	Microchip USA, How Military Tensions Are Driving the Next Semiconductor Chip Race (July 16, 2025) (last visited Aug. 12, 2025), available at https://www.microchipusa.com/industry-news/how-military-tensions-are-driving-the-next-semiconductor-chip-race?srsltid=AfmBOopQdXXTBoOGl_bluj9BHhwBFREsja-0SrRhCUKPHwTIW98FCBKI	X	X
1055	Another Historic Investment Secured Under President Trump, Articles, The White House (Mar. 3, 2025) (last visited July 14, 2025), available at https://www.whitehouse.gov/articles/2025/03/another-historic-investment-secured-under-president-trump/	X	X
1056	Sujai Shivakumar and Charles Wessner, Semiconductors and National Defense: What Are the Stakes?, Center for Strategic International Studies (June 8, 2022) (last visited July 14, 2025), available at https://www.csis.org/analysis/semiconductors-and-national-defense-what-are-stakes	X	X
1057	U.S., Taiwan, and Semiconductors: A Critical Supply Chain Partnership, Final Report, Project 2049 Institute (US-Taiwan Business Counsel June 21, 2023)	X	X
1058	Eric Lee, How Taiwan Underwrites the US Defense Industrial Complex, The Diplomat (Nov. 9, 2021) (last	X	X

Exhibit No.	Description	Filed	Served
	visited July 14, 2025), available at https://thediplomat.com/2021/11/how-taiwan-underwrites-the-us-defense-industrial-complex/		
1059	Reserved		
1060	Reserved		
1061	Reserved		
1062	Reserved		
1063	Silvia Pellegrino, What is TSMC?, Tech Monitor (Jan. 2, 2023) (last visited July 14, 2025), available at https://www.techmonitor.ai/what-is/what-is-tsmc/?cf-view	X	X
1064	Patent Owner's Response and Objections to Petitioner's First Request for Production of Documents (Contains Material Marked Highly Confidential – Attorneys' Eyes Only) FILED UNDER SEAL		
1065	Reserved		
1066	Reserved		
1067	U.S. Patent No. 7,067,919 to Watanabe et al. ("Watanabe'919")	X	X
1068	U.S. Patent No. 6,958,542 to Hasunuma et al. ("Hasunuma'542")	X	X
1069	JP4047324 file wrapper - excerpts and Certified Translation of excerpts and Certification of Translation	X	X
1070	16/12nm Technology	X	X

Exhibit No.	Description	Filed	Served
1071	Reserved		
1072	Petition for <i>Inter Partes</i> Review IPR2025-01212	X	X
1073	Removing Barriers to American Leadership in Artificial Intelligence, Presidential Actions, The White House (Jan. 23, 2025) (last visited July 14, 2025), available at https://www.whitehouse.gov/presidentialactions/2025/01/removing-barriers-to-american-leadership-in-artificial-intelligence/	X	X
1074	Office of Science and Technology Policy, Executive Office of the President of the United States, Winning the Race: America's AI Action Plan (July 2025)	X	X
1075	U.S.-China Economic and Security Review Commission, 2024 Report to Congress of the U.S.-China Economic and Security Review Commission, 118 Cong., 2d Sess. (2024)	X	X
1076	TSMC Expands Collaboration with Ansys by Integrating AI Technology to Accelerate 3D-IC Design, Ansys (Sept. 25, 2024) (last visited July 14, 2025), available at https://investors.ansys.com/news-releases/news-releasedetails/tsmc-expands-collaboration-ansys-integrating-ai-technology	X	X
1077	Cadence and TSMC Advance AI and 3D-IC Chip Design with Certified Design Solutions for TSMC's A16 and N2P Process Technologies, Cadence (Apr. 23, 2025) (last visited July 14, 2025), available at https://www.cadence.com/en_US/home/company/newsroom/pressreleases/pr/2025/cadence-and-tsmc-advance-ai-and-3d-ic-chipdesign-with-certified.html	X	X

Exhibit No.	Description	Filed	Served
1078	<p>Silent Giant TSMC Returns to the Peak of its Powers as the AI Boom Continues, Yahoo! finance (June 12, 2025), available at https://finance.yahoo.com/news/silent-giant-tsmc-returns-peak230300515.html?guccounter=1&guce_referrer=aHR0cHM6Ly93d3cuZ29vZ2xlLmNvbS8&guce_referrer_sig=AQAAAGbNeBi6fbz4U1LAPZACoSOpXFKhZ2d8Aeym1OTBUscShGSwm5cDQL_KDbidYk16TkPx7YtIzsB2YbOGeGdO4PchwSBFYrk3ftg3HWrMVSPIL1q7mWa7ZR5e6BG0tbKASjEzPE-8raiT0KakQ2cXTjpdVs4xTGUvCoXUGlVbDT</p>	X	X
1079	<p>Alex He, In the Global AI Chips Race, China Is Playing Catch-Up (September 18, 2024)</p>	X	X
1080	<p>Jeff Klearman, Decoding TSMC's Contribution to the AI and 5G Ecosystem (November 20, 2024), available at https://granitshares.com/institutional/us/en-us/research/decoding-tsmc-s-contribution-to-the-ai-and-5g-ecosystem</p>	X	X
1081	<p>Charlotte Trueman, Mayo Clinic to use Cerebras chips for medical AI models (January 9, 2024), available at https://www.datacenterdynamics.com/en/news/mayo-clinic-to-use-cerebras-chips-for-medical-ai-models/</p>	X	X
1082	<p>Vishal Subbiah, A Big Chip for Big Science: Watching the COVID-19 Virus in Action – Cerebras (December 14, 2021), available at https://www.cerebras.ai/blog/a-big-chip-for-big-science-watching-the-covid-19-virus-in-action</p>	X	X

CERTIFICATE OF SERVICE

The undersigned hereby certifies that on October 29, 2025 a true and correct copy of **EXHIBITS TSMC-1041–1058, TSMC-1063–1064, TSMC-1067–1070, and TSMC-1072–1082** and **PETITIONER'S UPDATED EXHIBIT LIST** was served in its entirety on the Patent Owner to the email addresses below:

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